

600V, 10A, Trench FS II Fast IGBT

General Description:

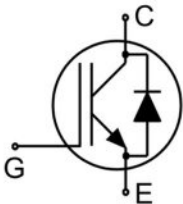
Using MJ's proprietary trench design and advanced FS (Field Stop) second generation technology, the 600V Trench FSII IGBT offers superior conduction and switching performances, and easy parallel operation;

Features

- ◆ Trench FSII Technology offering
- ◆ Very low $V_{CE(sat)}$
- ◆ High speed switching
- ◆ Positive temperature coefficient in $V_{CE(sat)}$
- ◆ Very tight parameter distribution
- ◆ High ruggedness, temperature stable behavior

Application

- ◆ Air Condition
- ◆ Inverters
- ◆ Motor drives



Schematic diagram



TO-252

Package Marking and Ordering Information

Device	Device Package	Device Marking
MJ10TD60BK	TO-252	MJ10TD60BK

Absolute Maximum Ratings ($T_c=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Units
Collector-Emitter Voltage	V_{CES}	600	V
Gate- Emitter Voltage	V_{GES}	± 30	V
Collector Current	I_C	20	A
Collector Current @ $T_c = 100^{\circ}\text{C}$	I_C	10	A
Pulsed Collector Current, t_p limited by T_{jmax}	I_{Cplus}	30	A
turn off safe operating area, $V_{CE}=600\text{V}$, $T_j=150^{\circ}\text{C}$	-	30	A
Diode Continuous Forward Current @ $T_c = 100^{\circ}\text{C}$	I_F	10	A
Diode Maximum Forward Current	I_{FM}	30	A
Power Dissipation @ $T_c = 25^{\circ}\text{C}$	P_D	83	W
Power Dissipation @ $T_c = 100^{\circ}\text{C}$	P_D	41.5	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +175	$^{\circ}\text{C}$
Maximum Temperature for Soldering	T_L	260	$^{\circ}\text{C}$
Short circuit withstand time $V_{GE}=15.0\text{V}$, $V_{CC}\leq 400\text{V}$, Allowed number of short circuits<1000Time between short circuits: $\geq 1.0\text{s}$, $T_j\leq 150^{\circ}\text{C}$	t_{sc}	5	us

Thermal Characteristic

Parameter	Symbol	Value	Units
Thermal Resistance, Junction to case for IGBT	$R_{\theta JC}$	1.80	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction to case for Diode	$R_{\theta JC}$	2.35	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	65	$^{\circ}\text{C}/\text{W}$

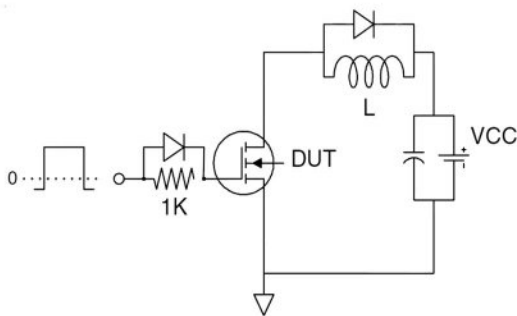
Electrical Characteristics (T_c=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions		Value			Units
				Min	Typ	Max	
Static Characteristics							
Collector-Emitter Breakdown Voltage	V _{(BR)CES}	V _{GE} =0V, I _{CE} =1mA		600	-	-	V
Collector-Emitter Leakage Current	I _{CES}	V _{GE} =0V, V _{CE} =600V		-	-	4	uA
Gate to Emitter Forward Leakage	I _{GES(F)}	V _{GE} =+30V, V _{CE} =0V		-	-	100	nA
Gate to Source Reverse Leakage	I _{GES(R)}	V _{GE} =-30V, V _{CE} =0V		-	-	100	nA
Collector-Emitter Saturation Voltage	V _{CE(sat)}	I _C =10A V _{GE} =15V	T _J =25°C	-	1.7	1.9	V
			T _J =100°C	-	1.9	-	V
Gate Threshold Voltage	V _{GE(th)}	I _C =1mA, V _{CE} =V _{GE}		4.0	5.0	6.0	V
Dynamic Characteristics							
Input Capacitance	C _{ies}	V _{CE} =25V, V _{GE} =0V, f=1MHz		-	1127	-	pF
Output Capacitance	C _{Oss}			-	40	-	pF
Reverse Transfer Capacitance	C _{rss}			-	24	-	pF
Total Gate Charge	Q _g	V _{CC} =480V, I _C =10A V _{GE} =15V		-	44	-	nC
Gate to Emitter Charge	Q _{ge}			-	10	-	nC
Gate to Collector Charge	Q _{gc}			-	19	-	nC
Short circuit collector current Max.1000 short circuits Time between short circuits: ≥1.0s	I _{C(SC)}	V _{GE} =15V, V _{CC} ≤400V, t _{sc} ≤5us, T _J ≤150°C		-	50	-	A
Switching Characteristics							
Turn-on Delay Time	t _{d(ON)}	V _{CC} =400V, I _C =10A V _{GE} =0/15V, R _g =5Ω Inductive Load		-	20	-	ns
Rise Time	t _r			-	15	-	ns
Turn-Off Delay Time	t _{d(OFF)}			-	73	-	ns
Fall Time	t _f			-	18	-	ns
Turn-On Switching Loss	E _{on}			-	0.21	-	mJ
Turn-Off Switching Loss	E _{off}			-	0.11	-	mJ
Total Switching Loss	E _{ts}			-	0.32	-	mJ

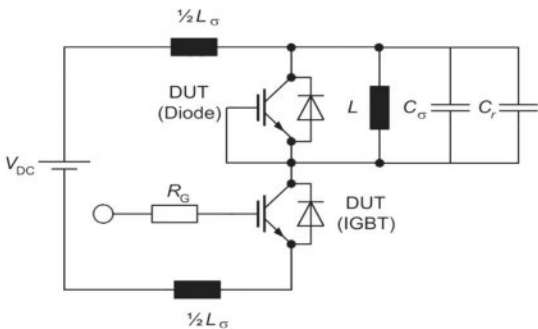
Electrical Characteristics of the Diode (Tc= 25°C unless otherwise specified):

Parameter	Symbol	Test Conditions	Rating			Units
			Min	Typ	Max	
Diode Forward Voltage	V _{FM}	I _F =10A	-	1.5	1.7	V
Reverse Recovery Time	T _{rr}	I _F =10A,di/dt=200A/uS	-	158	-	ns
Diode Peak Reverse Recovery Current	I _{RRM}		-	5.8	-	A
Reverse Recovery Charge	Q _{rr}		-	0.5	-	uC
Pulse width ttp≤380μs,δ≤2%						

Test Circuit

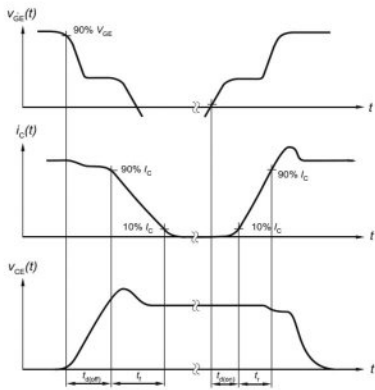


Gate Charge Test Circuit

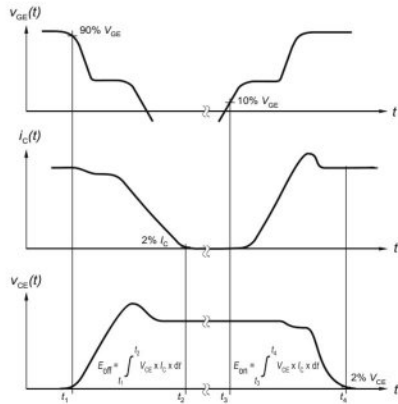


Switch Time Test Circuit

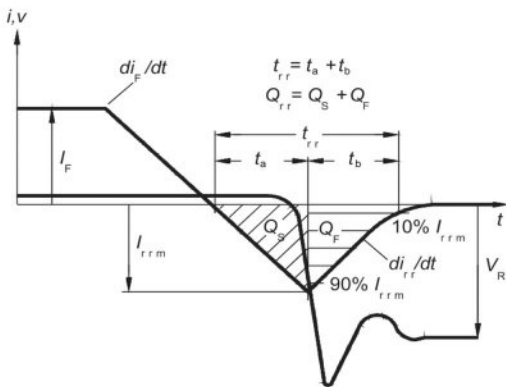
Switching characteristics



definition of switching times

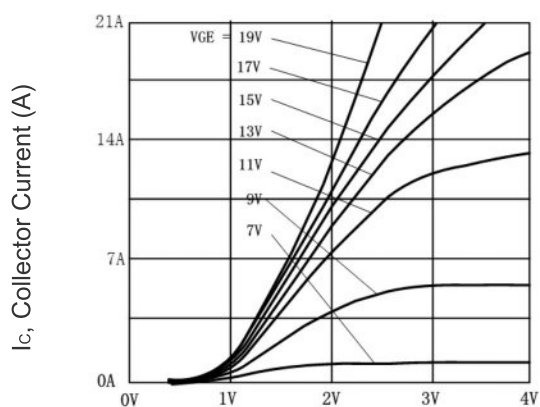


definition of switching losses

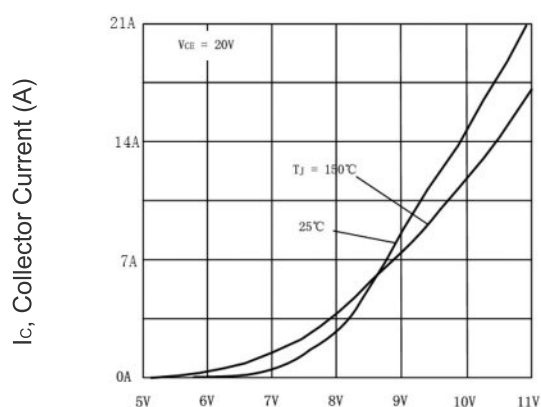


Definition of diode switching characteristics

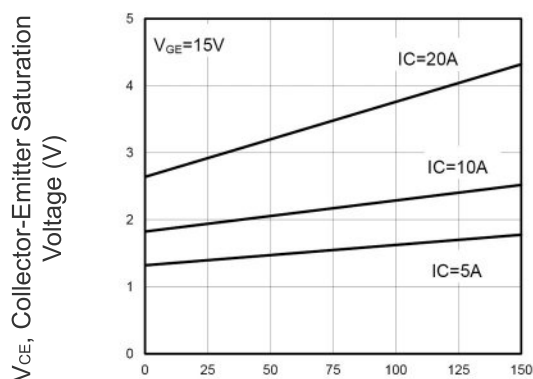
Typical Electrical and Thermal Characteristics



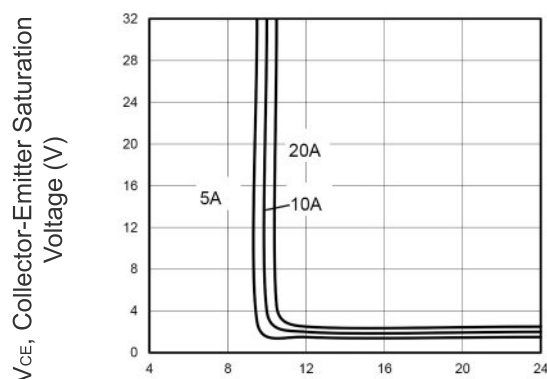
V_{CE} , Collector-Emitter Voltage (V)
Figure 1 Output Characteristics



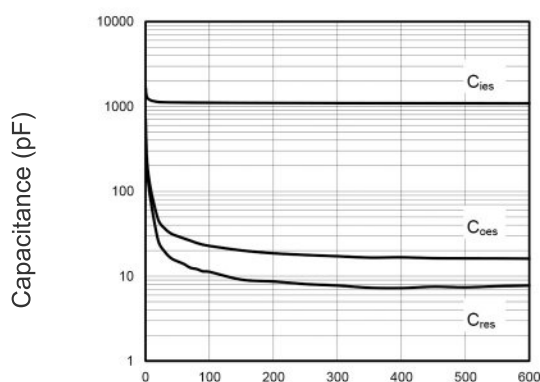
V_{GE} , Gate-Emitter Voltage (V)
Figure 2 Transfer Characteristics



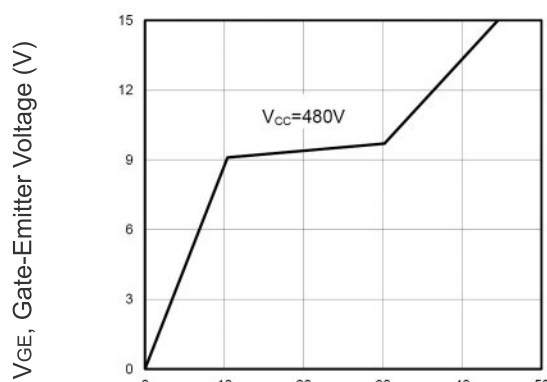
T_J , Junction Temperature ($^{\circ}\text{C}$)
Figure 3 V_{CEsat} vs. Case Temperature



V_{GE} , Gate-Emitter Voltage (V)
Figure 4 Saturation Voltage vs. V_{GE}

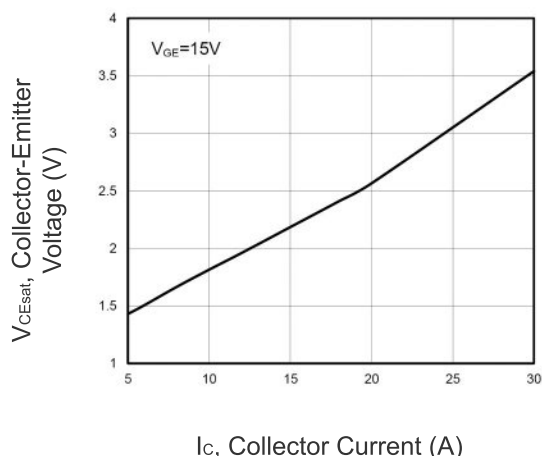
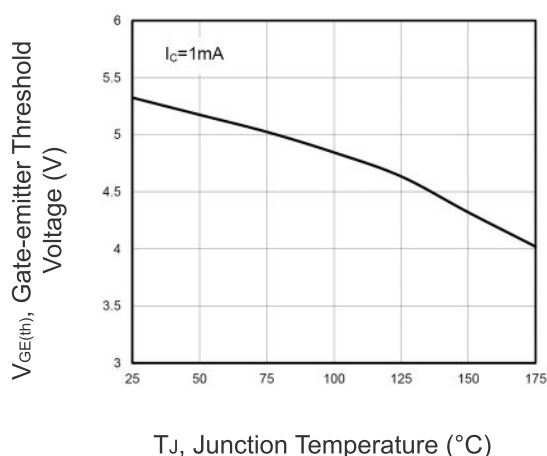
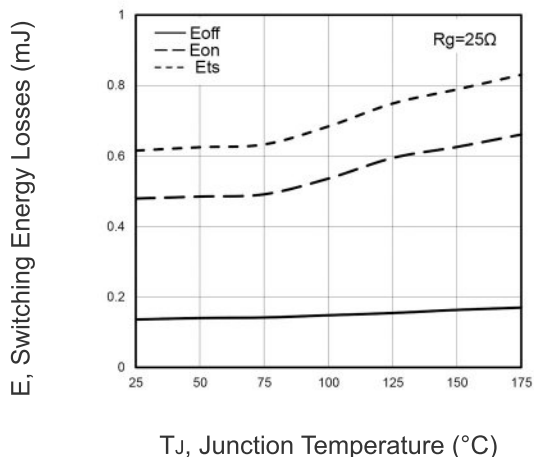
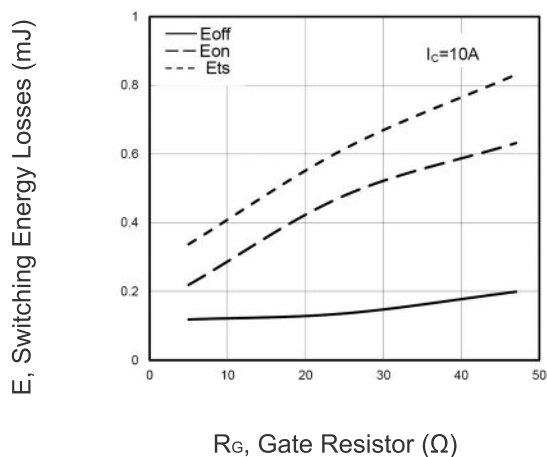
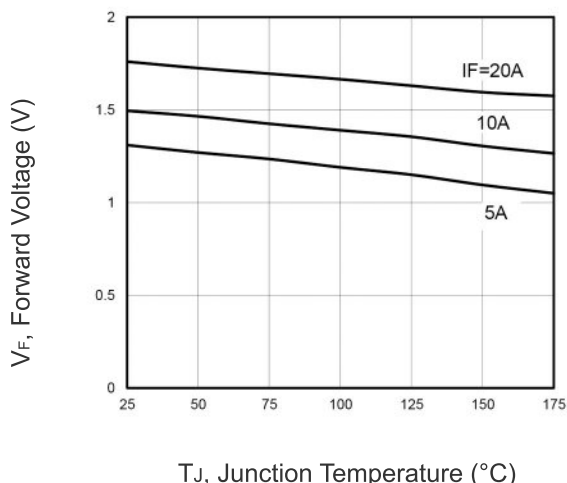
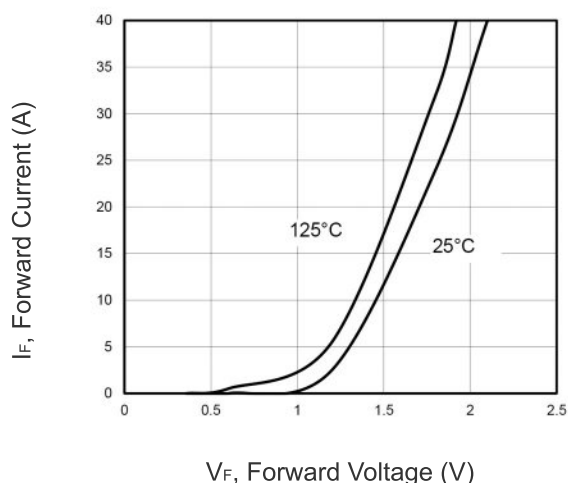


V_{CE} , Collector-Emitter Voltage (V)
Figure 5 Capacitance Characteristics



Q_G , Total Gate Charge (nC)
Figure 6 Gate charge waveform

Typical Electrical and Thermal Characteristics



Typical Electrical and Thermal Characteristics

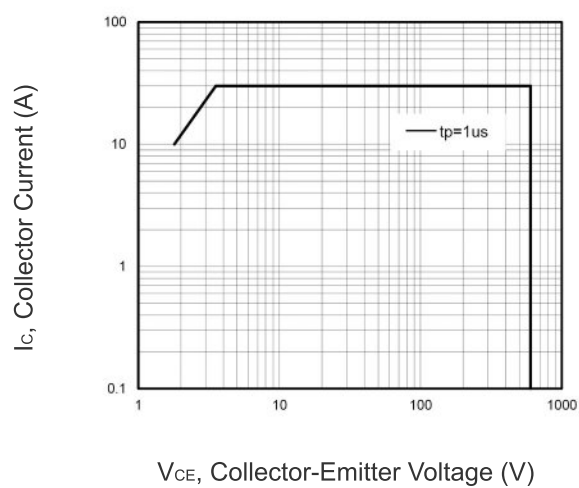
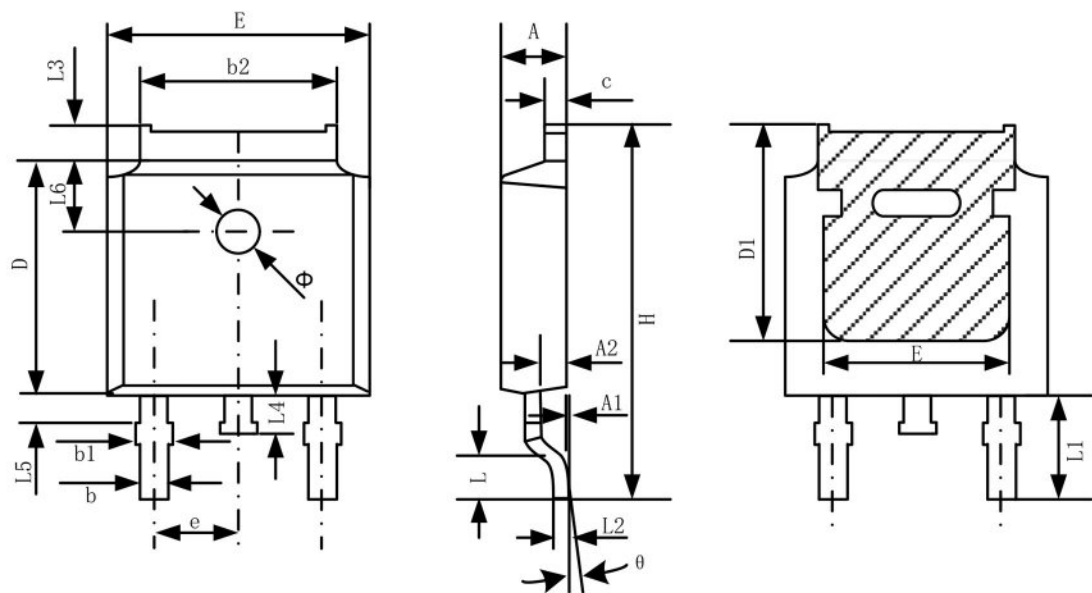


Figure 13 Forward Bias Safe Operating Area

TO-252-2 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.38	0.087	0.094
A1	0.00	0.10	0.000	0.004
A2	0.90	1.10	0.035	0.043
b	0.72	0.85	0.028	0.033
b1	0.72	0.90	0.028	0.035
b2	5.13	5.46	0.202	0.215
c	0.47	0.60	0.019	0.024
D	6.00	6.20	0.236	0.244
D1	5.25	--	0.207	--
E	6.50	6.70	0.256	0.264
E1	4.70	--	0.185	--
e	2.19	2.39	0.086	0.094
H	9.80	10.40	0.386	0.409
L	1.40	1.70	0.055	0.067
L1	2.90 REF		0.114 REF	
L2	0.508 BSC		0.020 BSC	
L3	0.90	1.25	0.035	0.049
L4	0.60	1.00	0.024	0.039
L5	0.15	0.75	0.006	0.030
L6	1.80 REF		0.071 REF	
Φ	1.20	1.40	0.047	0.055
θ	0°	8°	0°	0.31°

Attention:

Any and all MJ power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MJ power representative nearest you before using any MJ power products described or contained herein in such applications.

MJ power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MJ power products described or contained herein.

Specifications of any and all MJ power products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

MJ power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

In the event that any or all MJ power products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MJ power Semiconductor CO.,LTD.

Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MJ power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MJ power product that you intend to use.

This catalog provides information as of Sep.2010. Specifications and information herein are subject to change without notice.